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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10009822	FILING DATE 12/13/2001	CLASS 361	SUBCLASS	GAU 2835	EXAMINER KOENIGER LA VILLA
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****CONTINUING DATA VERIFIED:**
THIS APPLICATION IS A 371 OF PCT/JP01/03164 04/12/2001 *ok mm*

**** FOREIGN APPLICATIONS VERIFIED:**
JAPAN 17584/2000 01/26/2000
JAPAN 113006/2000 04/14/2000 *two ok*
JAPAN 372405/2000 12/07/2000 *m*

PG-PUB ☐ DO NOT PUBLISH ☐ RESCIND ☐

Foreign priority claimed ☐ yes ☐ no
35 USC 119 conditions met ☐ yes ☐ no
Verified and Acknowledged Examiners's initials *mm*

ATTORNEY DOCKET NO
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TITLE : Material of heat-dissipating plate on which semiconductor is mounted, method for fabricating the same, and ceramic package produced by using the same

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

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NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims 6	Print Claim for 0.0 1
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drawn 3	Figs. Drawn 7
		Print Figs 4	
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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